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**IMPORTANT NOTICE**  
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TO: U.S. Patent and Trademark Office  
Examiner: Thanh X. Luu  
Art Unit: 2878

DATE: November 26, 2002

FROM: Erin P. Madill

TIME: \_\_\_\_\_

TOTAL NO. OF PAGES, INCLUDING COVER: 18

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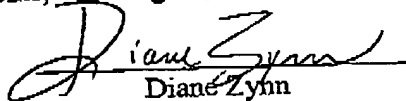
**MESSAGE:**

Patent Application No.: 09/654,550; Our Ref. 81754.0040  
I hereby certify that the following document:

- ☒ Amendment Under 37 C.F.R. § 1.116  
☒ Amendment Transmittal Letter

is being facsimiled to the Commissioner for Patents, Washington, D.C. 20231, for filing in the  
above-identified application.

November 26, 2002  
Date of Deposit

  
Diane Zynn

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TELECOPY/FAX NUMBER: 703-872-9319 ART UNIT 2878

CLIENT NUMBER: 81754.0040

ATTORNEY BILLING NUMBER: 3606

CONFIRMATION NUMBER: 703-305-0539 (return fax to Diane Zynn)

FORM PTO-1083

81754.0040

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Yoshiro IWASA

Serial No: 09/654,650

Filed: September 1, 2000

For: SEMICONDUCTOR DEVICE INCLUDING A LIGHT-RECEIVING ELEMENT (Amended)

Art Unit: 2878

Examiner: Luu, Thanh X.

I hereby certify that this correspondence is being transmitted via facsimile to (703) 872-9319: Commissioner for Patents, Washington D.C. 20231, on November 26, 2002	
Date of Deposit	
Name	Diane Zynn
Signature	<i>Diane Zynn</i>
Date	11/26/02

Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

Transmitted herewith is an amendment in the above-identified application.

- ☐ Small entity status has been claimed. See 37 CFR § 1.27.
- ☐ A certified copy of \_\_\_ Patent Application No. \_\_\_ filed \_\_\_ from which priority is claimed under 35 U.S.C. § 119 is enclosed.
- ☐ A Notice Of Change Of Attorney's Address and Associate Power Of Attorney is enclosed.
- ☒ No additional fee is required.

The fee has been calculated as shown below:

	(Col. 1) CLAIMS REMAINING AFTER AMENDMENT		(Col. 2) HIGHEST NUMBER PREVIOUSLY PAID FOR	(Col. 3) PRESENT EXTRA*	LG/SM \$ ENTITY FEE	ADD'L FEE DUE
TOTAL CLAIMS FEE	9	-	20	**	0	\$ 0
INDEPENDENT CLAIMS FEE	3	-	7	---	4	\$ 0
FIRST PRESENTATION OF MULTIPLE DEPENDENT CLAIMS					LARGE ENTITY FEE = \$280 SMALL ENTITY FEE = \$140	\$ 0
Independent Claims: 5, 13, 18					TOTAL	\$ 0

- \* If the entry in Col. 1 is less than the entry in Col. 2, write "0" in Col. 3.
- If the "Highest Number Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.
- If the "Highest Number Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space. The "Highest Number Previously Paid For" (Total or Independent) is the highest number found from the equivalent box on Col. 1 of a prior amendment or the number of claims originally filed.

- ☐ Please charge the fee of \$0 for the additional claim fees to Deposit Account No. 50-1314. A copy of this sheet is enclosed.
- ☐ A check in the amount of \$ 0 to cover the extension fee is enclosed. A copy of this sheet is enclosed.
- ☒ The Commissioner is hereby authorized to charge any deficiencies of fees associated with this communication or credit any overpayment to Deposit Account No. 50-1314. A copy of this sheet is enclosed.
- ☒ Any filing fees under 37 C.F.R. § 1.16 for the presentation of extra claims
- ☒ Any patent application processing fees under 37 C.F.R. § 1.17

Respectfully submitted,  
HOGAN & HARTSON L.L.P.

By: *Erin P. Madill*  
Erin P. Madill  
Registration No. 46,893  
Attorney for Applicant(s)

Date: November 26, 2002

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PATENT  
81754.0040

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Yoshiro IWASA

Serial No: 09/654,550

Filed: September 1, 2000

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Art Unit: 2878

Examiner: Thanh X. Luu

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November 26, 2002

Date of Deposit

Erin P. Madill

Name

Signature

11/26/02

Date

AMENDMENT UNDER 37 C.F.R. § 1.116Box AF  
Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

In response to the Final Office Action dated August 29, 2002, please amend  
the above-referenced application as follows:

IN THE CLAIMS:

Please cancel claims 4 and 7-10 without prejudice.

Please replace the text of claims 2, 3, 5 and 11-16 with the following text:

2. (Twice Amended) A semiconductor device according to claim 3,  
wherein the optical signal transfer device is an optical fiber.
3. (Twice Amended) A semiconductor device comprising:  
a semiconductor chip mounted on a mounting substrate and a light-receiving  
element formed in the semiconductor chip for receiving an optical signal;  
an optical signal transfer device embedded in the mounting substrate,  
wherein the optical signal transfer device directly contacts the light-receiving  
element for transferring the optical signal into the semiconductor chip; and